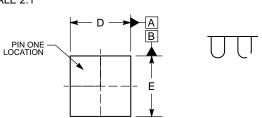
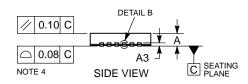
QFNW24 4x4, 0.5P CASE 484AA ISSUE A

1 24 SCALE 2:1

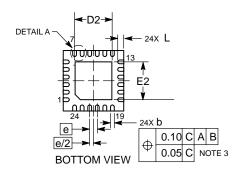
DATE 07 AUG 2018



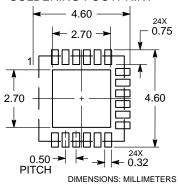




TOP VIEW



RECOMMENDED SOLDERING FOOTPRINT



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM THE TERMINAL TIP.

 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

GENERIC MARKING DIAGRAM*

°xxxxxx XXXXXX ALYW

XXXXXX = Specific Device Code

= Assembly Location Α

= Wafer Lot L Υ = Year W = Work Week

= Pb ïFree Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb ïFree indicator, "G" or microdot " ", may or may not be present. Some products may not follow the Generic Marking.